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(57)ABSTRACT

A substrate according to an embodiment includes an insulating layer having a grain formed therein extending in a first direction; and a circuit pattern disposed on the insulating layer; wherein the insulating layer includes an upper surface and a plurality of outer side surfaces; wherein the plurality of outer side surfaces includes: a first outer side surface extending in the same first direction as the first direction having the grain formed in the insulating layer; and a second outer side surface extending in a second direction different from the first direction and excluding the first outer side surface, wherein the first outer side surface has a first surface roughness; and wherein the second outer side surface has a second surface roughness different from the first surface roughness.

